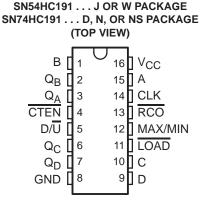
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 13 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Single Down/Up Count-Control Line
- Look-Ahead Circuitry Enhances Speed of Cascaded Counters
- Fully Synchronous in Count Modes
- Asynchronously Presettable With Load Control

#### description/ordering information

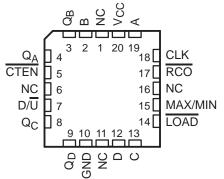
The 'HC191 devices are 4-bit synchronous, reversible, up/down binary counters. Synchronous counting operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the steering logic. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters.

The outputs of the four flip-flops are triggered on a low- to high-level transition of the clock (CLK) input if the count-enable (CTEN) input is low. A high at  $\overrightarrow{\text{CTEN}}$  inhibits counting. The direction of the count is determined by the level of the down/up (D/U) input. When D/U is low, the counter counts up, and when D/U is high, it counts down.



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

SN54HC191 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

	UR	DERING INFO	JRIVIATION	
TA	PACKAG	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC191N	SN74HC191N
		Tube of 40	SN74HC191D	
–40°C to 85°C	SOIC – D	Reel of 2500	SN74HC191DR	HC191
		Reel of 250	SN74HC191DT	
	SOP – NS	Reel of 2000	SN74HC191NSR	HC191
CDIP – J		Tube of 25	SNJ54HC191J	SNJ54HC191J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC191W	SNJ54HC191W
	LCCC – FK	Tube of 55	SNJ54HC191FK	SNJ54HC191FK

### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-3853s, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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#### description/ordering information (continued)

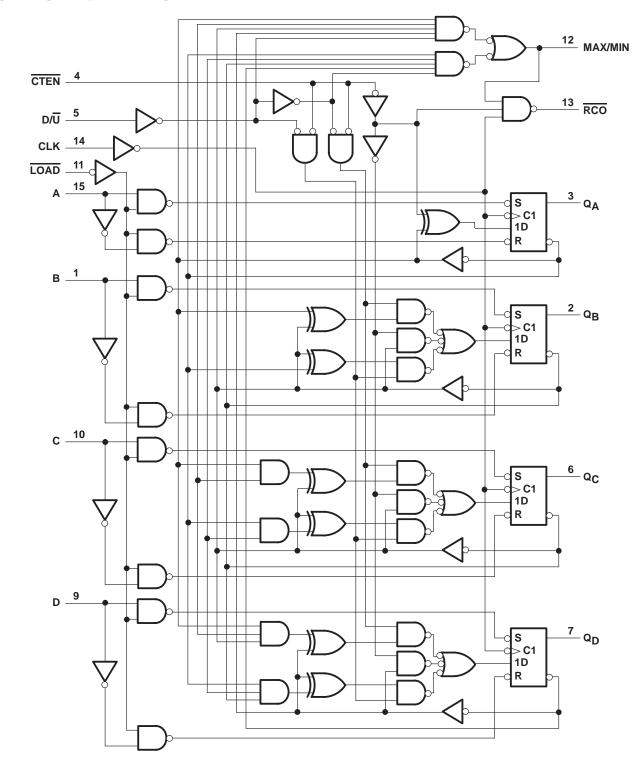
These counters feature a fully independent clock circuit. Change at the control ( $\overline{\text{CTEN}}$  and  $D/\overline{U}$ ) inputs that modifies the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter is dictated solely by the condition meeting the stable setup and hold times.

These counters are fully programmable; that is, each of the outputs can be preset to either level by placing a low on the load ( $\overline{LOAD}$ ) input and entering the desired data at the data inputs. The output changes to agree with the data inputs independently of the level of CLK. This feature allows the counters to be used as modulo-N dividers simply by modifying the count length with the preset inputs.

Two outputs are available to perform the cascading function: ripple clock ( $\overline{\text{RCO}}$ ) and maximum/minimum (MAX/MIN) count. MAX/MIN produces a high-level output pulse with a duration approximately equal to one complete cycle of the clock while the count is zero (all outputs low) counting down, or maximum (9 or 15) counting up.  $\overline{\text{RCO}}$  produces a low-level output pulse under those same conditions, but only while CLK is low. The counters can be cascaded easily by feeding  $\overline{\text{RCO}}$  to  $\overline{\text{CTEN}}$  of the succeeding counter if parallel clocking is used, or to CLK if parallel enabling is used. MAX/MIN can be used to accomplish look ahead for high-speed operation.



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003



logic diagram (positive logic)

Pin numbers shown are for the D, J, N, NS, and W packages.

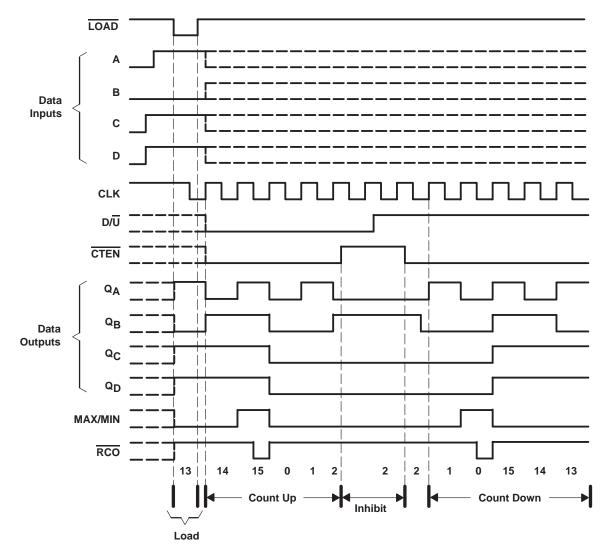


SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

#### typical load, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Load (preset) to binary 13
- 2. Count up to 14, 15 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 15, 14, and 13





SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>		
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (se	e Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	c) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T <sub>stg</sub>		–65°C to 150°C

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

			SI	N54HC19	91	SN	174HC19	)1	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		$\Lambda$ CC = 6 $\Lambda$	4.2			4.2			
		$V_{CC} = 2 V$			0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35			1.35	V
		$\Lambda$ CC = 6 $\Lambda$			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t / \Delta v^{\ddagger}$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns
		$V_{CC} = 6 V$			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

If this device is used in the threshold region (from V<sub>IL</sub>max = 0.5 V to V<sub>IH</sub>min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t<sub>t</sub> = 1000 ns and V<sub>CC</sub> = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54H	IC191	SN74H	C191	
PARAMETER	TEST CO	ONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		l <sub>OH</sub> = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
∨он	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
lj	VI = VCC  or  0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

				T <sub>A</sub> =	25°C	SN54H	IC191	SN74H	C191	
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		4.2		2.8		3.3	
fclock	Clock frequency		4.5 V		21		14		17	MHz
			6 V		24		16		19	
			2 V	120		180		150		
		LOAD low	4.5 V	24		36		30		
	Pulse duration		6 V	21		31		26		
tw	Pulse duration		2 V	120		180		150		ns
		CLK high or low	4.5 V	24		36		30		
			6 V	21		31		26		
			2 V	150		230		188		
		Data before LOAD↑	4.5 V	30		46		38		
			6 V	25		38		32		
			2 V	205		306		255		
		CTEN before CLK <sup>↑</sup>	4.5 V	41		61		51		
	O a true time a		6 V	35		53		44		
t <sub>su</sub>	Setup time		2 V	205		306		255		ns
		D/U before CLK↑	4.5 V	41		61		51		
			6 V	35		53		44		
			2 V	150		225		190		
		LOAD inactive before CLK↑	4.5 V	30		45		38		
			6 V	25		38		32		
			2 V	5		5		5		
		Data after LOAD↑	4.5 V	5		5		5		
			6 V	5		5		5		
	t <sub>h</sub> Hold time		2 V	5		5		5		
t <sub>h</sub>		CTEN after CLK↑	4.5 V	5		5		5		ns
			6 V	5		5		5		
			2 V	5		5		5		
		D/U after CLK↑	4.5 V	5		5		5		
			6 V	5		5		5		



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

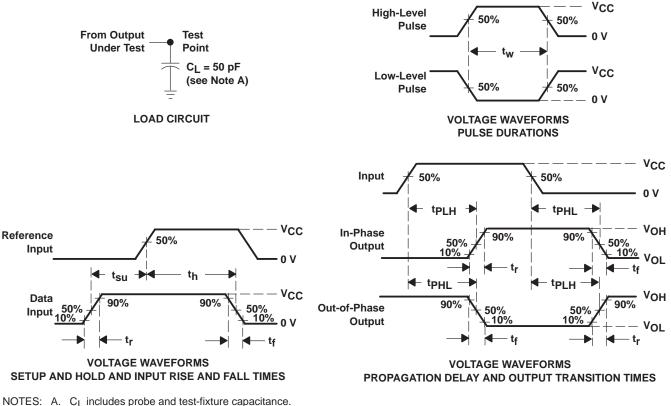
	FROM	то		T,	<b>Α</b> = 25°C	>	SN54F	IC191	SN74H	IC191	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	4.2	8		2.8		3.3		
fmax			4.5 V	21	42		14		17		MHz
			6 V	24	48		16		19		
			2 V		130	264		396		330	
	LOAD	Any Q	4.5 V		40	53		79		66	
			6 V		33	45		67		56	
			2 V		135	240		360		300	
	A, B, C, or D	Q <sub>A</sub> , Q <sub>B</sub> , Q <sub>C</sub> , or Q <sub>D</sub>	4.5 V		36	48		72		60	
			6 V		30	41		61		51	
			2 V		58	120		180		150	
		RCO	4.5 V		17	24		36		30	
			6 V		14	21		31		26	
		2 V		107	192		288		240		
	CLK	Any Q	4.5 V		31	38		58		48	
			6 V		26	32		49		41	
<sup>t</sup> pd			2 V		123	252		378		315	ns
		MAX/MIN	4.5 V		39	50		76		63	
			6 V		32	43		65		54	
			2 V		102	228		342		285	
		RCO	4.5 V		29	46		68		57	
	D/U		6 V		24	38		59		49	
	D/U		2 V		86	192		288		240	
		MAX/MIN	4.5 V		24	38		58		48	
			6 V		20	32		49		41	
			2 V		50	132		198		165	
	CTEN	RCO	4.5 V		15	26		40		33	
			6 V		13	23		34		28	
			2 V		38	75		110		95	
tt		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	50	pF



SCLS121D - DECEMBER 1982 - REVISED OCTOBER 2003



### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CI includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- C. For clock inputs, fmax is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tPLH and tPHL are the same as tpd.

#### Figure 1. Load Circuit and Voltage Waveforms





### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86891012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86891012A SNJ54HC 191FK	Samples
5962-8689101EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8689101EA SNJ54HC191J	Samples
SN54HC191J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC191J	Samples
SN74HC191D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC191	Samples
SN74HC191DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC191	Samples
SN74HC191DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC191	Samples
SN74HC191DT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC191	Samples
SN74HC191N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC191N	Samples
SN74HC191NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC191N	Samples
SN74HC191NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC191	Samples
SNJ54HC191FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86891012A SNJ54HC 191FK	Samples
SNJ54HC191J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8689101EA SNJ54HC191J	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect. NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.



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<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54HC191, SN74HC191 :

• Catalog : SN74HC191

• Military : SN54HC191

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

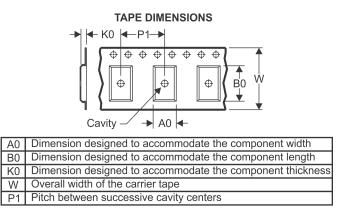
# PACKAGE MATERIALS INFORMATION

Texas Instruments

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC191DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC191NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC191DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC191NSR	SO	NS	16	2000	853.0	449.0	35.0



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### TUBE



Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-86891012A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74HC191D	D	SOIC	16	40	507	8	3940	4.32
SN74HC191N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC191N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC191NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC191NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54HC191FK	FK	LCCC	20	1	506.98	12.06	2030	NA

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N\*\*) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

# D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



# **NS0016A**



# **PACKAGE OUTLINE**

SOP - 2.00 mm max height

SOP



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- Per ASME Y14.5M.
  This drawing is subject to change without notice.
  This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



# NS0016A

# **EXAMPLE BOARD LAYOUT**

### SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# NS0016A

# **EXAMPLE STENCIL DESIGN**

### SOP - 2.00 mm max height

SOP



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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